

## IGBT Module

### Features:

- Low Saturation Voltage:  $V_{CE(sat)} = 1.80V @ I_C = 600A, T_C=25^\circ C$
- Low Switching Loss
- 100% RBSOA Tested ( $2 \times I_C$ )
- Low Stray Inductance
- Lead Free, Compliant with RoHS Requirement



### Applications:

- High Power Converters
- Motor Drives
- UPS Systems
- Wind Turbines

### Maximum Rated Values of IGBT( $T_C=25^\circ C$ unless otherwise specified)

$V_{CES}$	Collector-Emitter Blocking Voltage		1200	V
$V_{GES}$	Gate-Emitter Voltage		$\pm 20$	V
$I_C$	Continuous Collector Current	$T_C = 80^\circ C,$	600	A
		$T_C = 25^\circ C$	1130	A
$I_{CM}$	Repetitive Peak Collector Current	$T_J = 175^\circ C$	1200	A
$P_D$	Maximum Power Dissipation per IGBT	$T_C = 25^\circ C$ $T_{Jmax}=175^\circ C$	3060	W

## Electrical Characteristics of IGBT ( $T_C=25^\circ\text{C}$ unless otherwise specified)

### Static characteristics

Symbol	Description	Conditions	Min	Typ	Max	Unit
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C = 1\text{mA}, V_{CE} = V_{GE}$	5.0	5.5	6.0	V
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$I_C = 600\text{A}, V_{GE} = 15\text{V}$	$T_J = 25^\circ\text{C}$	1.80	2.10	V
			$T_J = 125^\circ\text{C}$	2.10		V
$I_{CES}$	Collector-Emitter Leakage Current	$V_{GE} = 0\text{V}, V_{CE} = V_{CES}, T_J = 25^\circ\text{C}$			1	mA
$I_{GES}$	Gate-Emitter Leakage Current	$V_{GE} = \pm 20\text{V}, V_{CE} = 0\text{V}, T_J = 25^\circ\text{C}$			400	nA
$C_{ies}$	Input Capacitance	$V_{CE} = 25\text{V}, V_{GE} = 0\text{V}, f = 1\text{MHz}$		51.0		nF
$C_{oes}$	Output Capacitance			3.30		nF

### Switching Characteristics

Symbol	Description	Conditions	$T_J = 25^\circ\text{C}$			Unit
			Min	Typ	Max	
$t_{d(on)}$	Turn-on Delay Time	$V_{CC} = 600\text{V}, I_C = 600\text{A}, R_G = 5\ \Omega, V_{GE} = \pm 15\text{V}, \text{Inductive Load}$		1340		ns
			$T_J = 125^\circ\text{C}$	1270		
			$T_J = 150^\circ\text{C}$	1265		
$t_r$	Rise Time		$T_J = 25^\circ\text{C}$	195		ns
			$T_J = 125^\circ\text{C}$	205		
			$T_J = 150^\circ\text{C}$	185		
$t_{d(off)}$	Turn-off Delay Time		$T_J = 25^\circ\text{C}$	1020		ns
			$T_J = 125^\circ\text{C}$	1050		
			$T_J = 150^\circ\text{C}$	1070		
$t_f$	Fall Time		$T_J = 25^\circ\text{C}$	175		ns
			$T_J = 125^\circ\text{C}$	190		
			$T_J = 150^\circ\text{C}$	195		
$E_{on}$	Turn-on Switching Loss	$T_J = 25^\circ\text{C}$	16.9		mJ	
		$T_J = 125^\circ\text{C}$	22.4			
		$T_J = 150^\circ\text{C}$	24.2			

E <sub>off</sub>	Turn-off Switching Loss	V <sub>CC</sub> = 600V, I <sub>C</sub> = 600A, R <sub>G</sub> = 5 Ω, V <sub>GE</sub> = ±15V, Inductive Load	T <sub>J</sub> = 25°C	101.0	mJ
			T <sub>J</sub> = 125°C	120.6	
			T <sub>J</sub> = 150°C	124.7	
Q <sub>g</sub>	Total Gate Charge		T <sub>J</sub> = 25°C	3640	nC
RBSOA	RBSOA	I <sub>C</sub> =1200A, V <sub>CC</sub> =960V, V <sub>p</sub> =1200V, R <sub>g</sub> = 15Ω, V <sub>GE</sub> =+15V to 0V, T <sub>J</sub> =150°C	Trapezoid		
R <sub>θJC</sub>	IGBT Thermal Resistance: Junction-To-Case			0.05	°C/W

### Maximum Rated Values of Diode (T<sub>C</sub>=25°C unless otherwise specified)

V <sub>RRM</sub>	Repetitive Peak Reverse Voltage	1200	V
I <sub>F</sub>	Diode Continuous Forward Current	600	A
I <sub>FM</sub>	Diode Maximum Forward Current	1200	A

### Electrical Characteristics of Diode

Symbol	Description	Conditions	Min	Typ	Max	Unit
V <sub>FM</sub>	Forward Voltage	I <sub>F</sub> = 600A , V <sub>GE</sub> = 0V	T <sub>J</sub> = 25°C	2.00	2.30	V
			T <sub>J</sub> = 125°C	2.20		
			T <sub>J</sub> = 150°C	2.15		
I <sub>rr</sub>	Peak Reverse Recovery Current	I <sub>F</sub> =600A, di/dt =2900A/μs, V <sub>rr</sub> = 600V, V <sub>GE</sub> = -15V	T <sub>J</sub> = 25°C	205		A
			T <sub>J</sub> = 125°C	290		
			T <sub>J</sub> = 150°C	305		
Q <sub>rr</sub>	Reverse Recovery Charge	I <sub>F</sub> =600A, di/dt =2900A/μs, V <sub>rr</sub> = 600V, V <sub>GE</sub> = -15V	T <sub>J</sub> = 25°C	25.6		μC
			T <sub>J</sub> = 125°C	52.8		
			T <sub>J</sub> = 150°C	61.4		
E <sub>rec</sub>	Reverse Recovery Energy	I <sub>F</sub> =600A, di/dt =2900A/μs, V <sub>rr</sub> = 600V, V <sub>GE</sub> = -15V	T <sub>J</sub> = 25°C	13.5		mJ
			T <sub>J</sub> = 125°C	27.6		
			T <sub>J</sub> = 150°C	31.7		
R <sub>θJC</sub>	Diode Thermal Resistance: Junction-To-Case			0.10		°C/W

## Internal NTC-Thermistor Characteristics

R <sub>25</sub>	T <sub>C</sub> =25°C	5		kΩ
ΔR/R	T <sub>C</sub> =100°C, R <sub>100</sub> =481Ω		±5	%
P <sub>25</sub>	T <sub>C</sub> =25°C	50		mW
B <sub>25/50</sub>	$R_2=R_{25} \exp[B_{25/50}(1/T_2-1/(298.15K))]$	3380		K
B <sub>25/80</sub>	$R_2=R_{25} \exp[B_{25/80}(1/T_2-1/(298.15K))]$	3440		K

## Module

Symbol	Description	Min	Typ	Max	Unit
V <sub>iso</sub>	Isolation Voltage(All Terminals Shorted)      f = 50Hz, 1minute			2500	V
T <sub>J</sub>	Maximum Junction Temperature			175	°C
T <sub>JOP</sub>	Maximum Operating Junction Temperature Range	-40		+150	°C
T <sub>stg</sub>	Storage Temperature	-40		+125	°C
R <sub>θCS</sub>	Case-To-Sink (Conductive Grease Applied)		0.1		°C/W
T	Power Terminals Screw:M5	3.0		5.0	N·m
T	Mounting Screw:M6	4.0		6.0	N·m
G	Weight		330		g

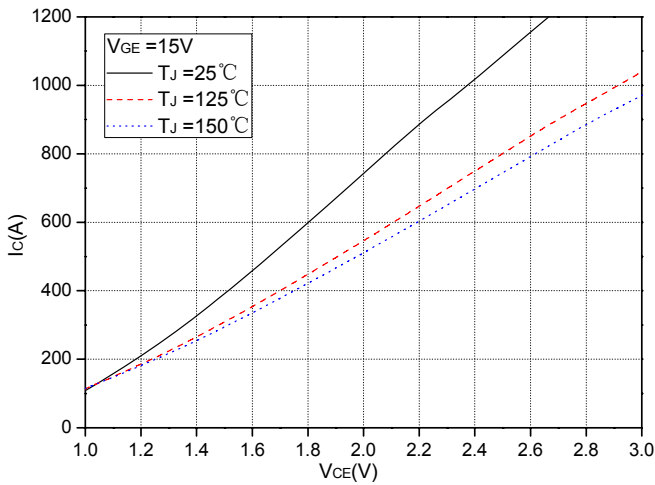


Fig.1 Typical Saturation Voltage Characteristics

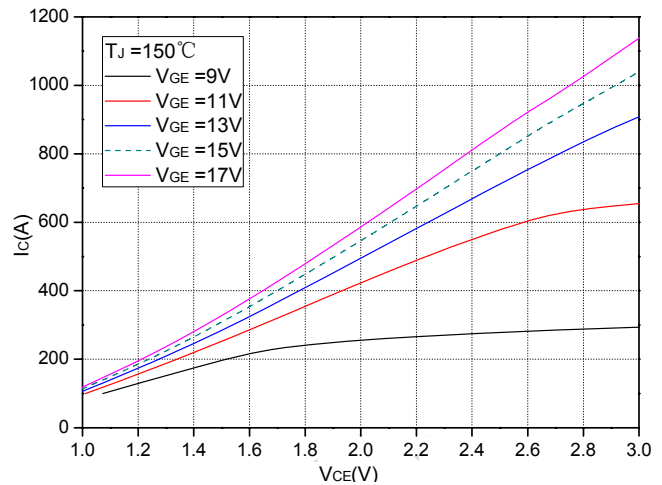


Fig.2 Typical Output Characteristics

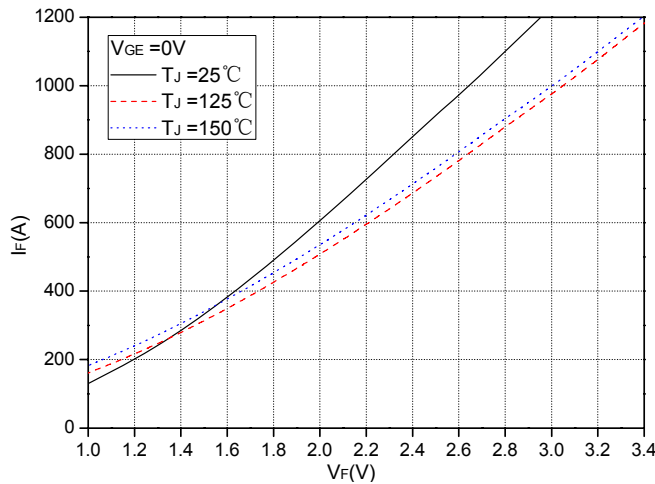


Fig.3 Forward Characteristics of Diode

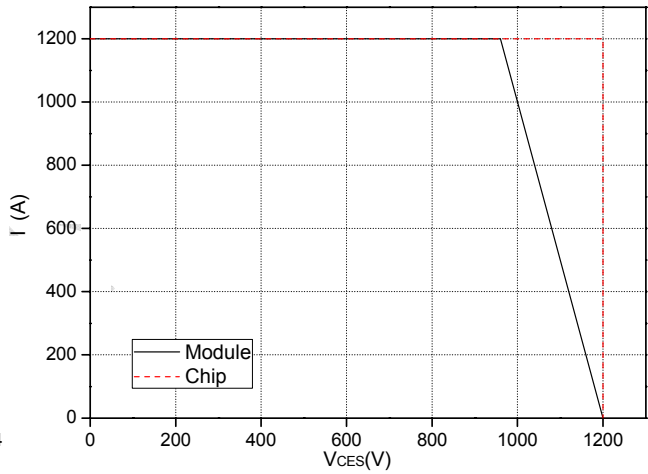


Fig.4 Reverse Bias Safe Operation Area (RBSOA)

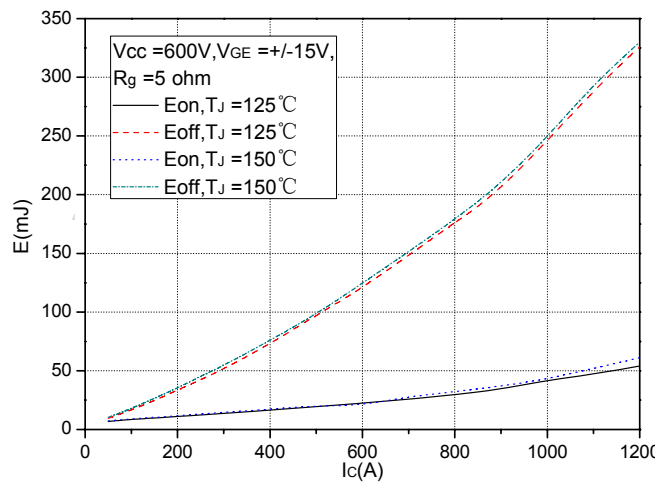


Fig.5 Typical Switching Loss vs. Collector Current

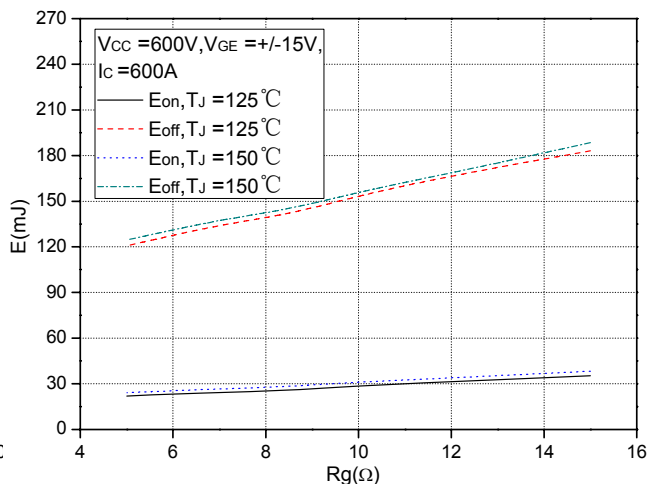


Fig.6 Typical Switching Loss vs. Gate Resistance

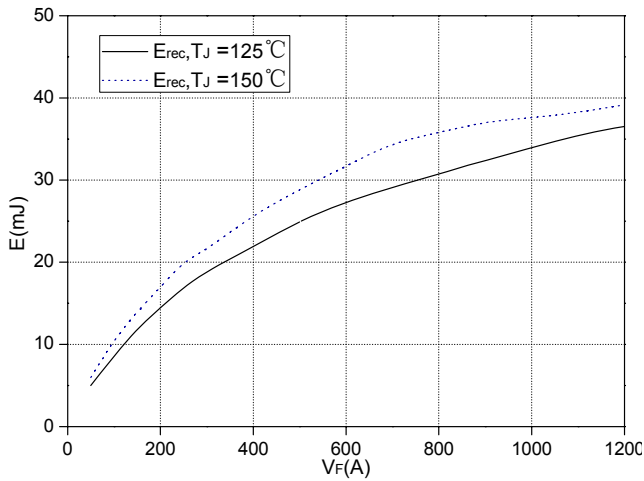


Fig.7 Typical Switching Loss vs. Collector Current

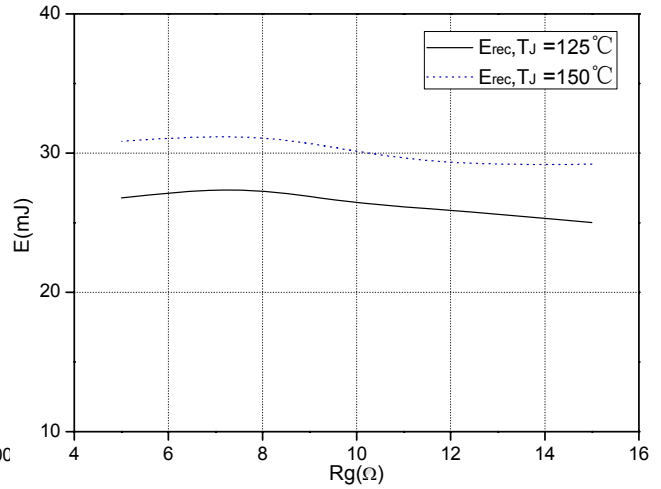


Fig.8 Typical Switching Loss vs. Gate Resistance

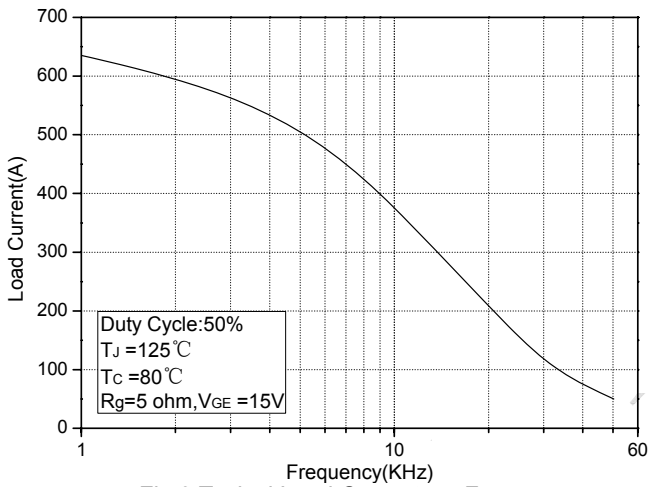


Fig.9 Typical Load Current vs. Frequency

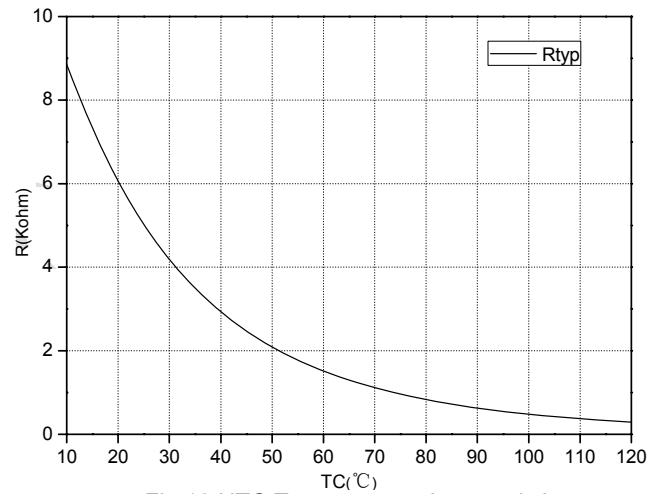


Fig.10 NTC Temperature characteristics

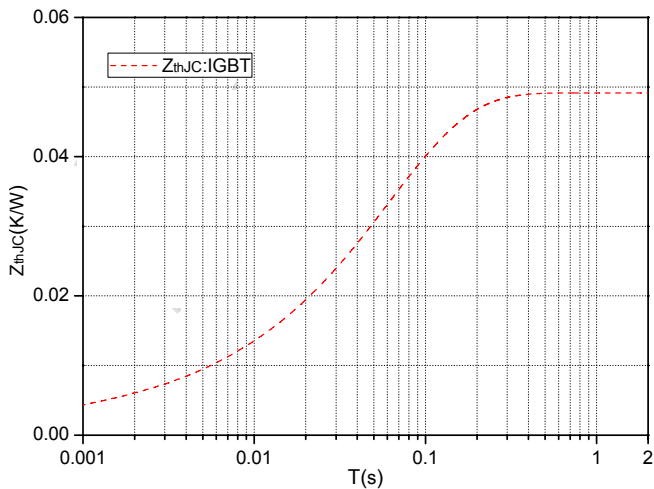


Fig.11 Transient thermal impedance (IGBT)

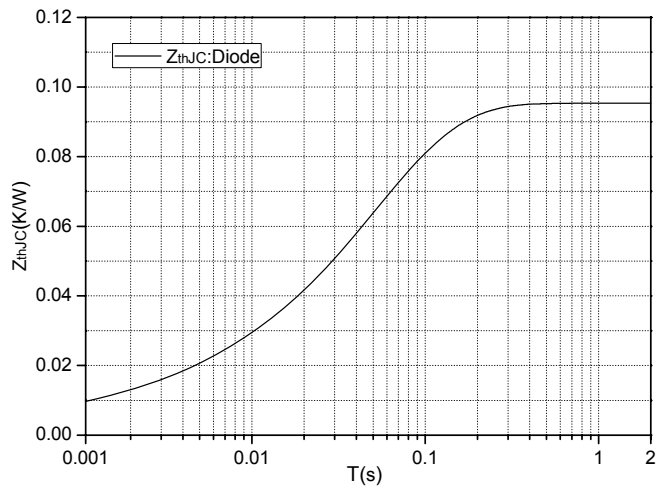


Fig.12 Transient thermal impedance (Diode)

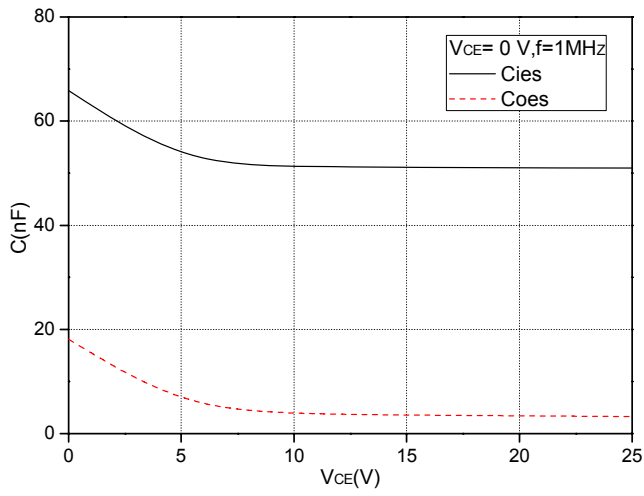
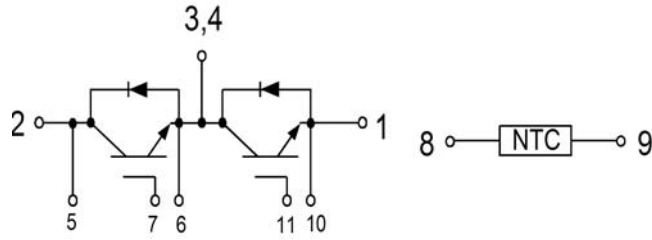


Fig.13 Capacitance Characteristics

## Internal Circuit



## Package Outline (Unit: mm):

